



**THE DATASHEET OF  
BAL99E6327HTSA1**

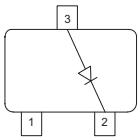


### Silicon Switching Diode

- For high-speed switching applications
- Pb-free (RoHS compliant) package<sup>1)</sup>
- Qualified according AEC Q101



### BAL99



Type	Package	Configuration	Marking
BAL99	SOT23	single	JFs

**Maximum Ratings** at  $T_A = 25^\circ\text{C}$ , unless otherwise specified

Parameter	Symbol	Value	Unit
Diode reverse voltage	$V_R$	80	V
Peak reverse voltage-	$V_{RM}$	85	
Forward current	$I_F$	250	mA
Peak forward current	$I_{FM}$	-	
Surge forward current, $t = 1 \mu\text{s}$	$I_{FS}$	4.5	A
Total power dissipation $T_S \leq 54^\circ\text{C}$	$P_{tot}$	370	mW
Junction temperature	$T_j$	150	$^\circ\text{C}$
Storage temperature	$T_{stg}$	-65 ... 150	

### Thermal Resistance

Parameter	Symbol	Value	Unit
Junction - soldering point <sup>2)</sup>	$R_{thJS}$	$\leq 260$	K/W

<sup>1</sup>Pb-containing package may be available upon special request

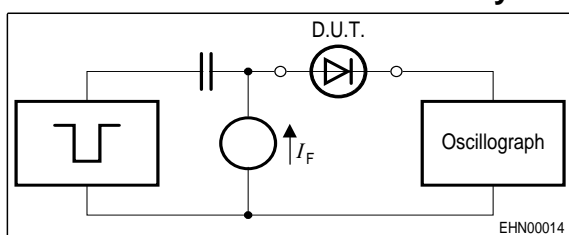
<sup>2</sup>For calculation of  $R_{thJA}$  please refer to Application Note Thermal Resistance

**Electrical Characteristics** at  $T_A = 25^\circ\text{C}$ , unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
<b>DC Characteristics</b>					
Breakdown voltage $I_{(BR)} = 100 \mu\text{A}$	$V_{(BR)}$	85	-	-	V
Reverse current $V_R = 70 \text{ V}$ $V_R = 25 \text{ V}, T_A = 150^\circ\text{C}$ $V_R = 70 \text{ V}, T_A = 150^\circ\text{C}$	$I_R$	-	-	1 30 50	$\mu\text{A}$
Forward voltage $I_F = 1 \text{ mA}$ $I_F = 10 \text{ mA}$ $I_F = 50 \text{ mA}$ $I_F = 150 \text{ mA}$	$V_F$	-	-	715 855 1000 1250	mV

**AC Characteristics**

Diode capacitance $V_R = 0 \text{ V}, f = 1 \text{ MHz}$	$C_T$	-	-	1.5	pF
Reverse recovery time $I_F = 10 \text{ mA}, I_R = 10 \text{ mA}$ , measured at $I_R = 1 \text{ mA}$ , $R_L = 100 \Omega$	$t_{rr}$	-	-	4	ns

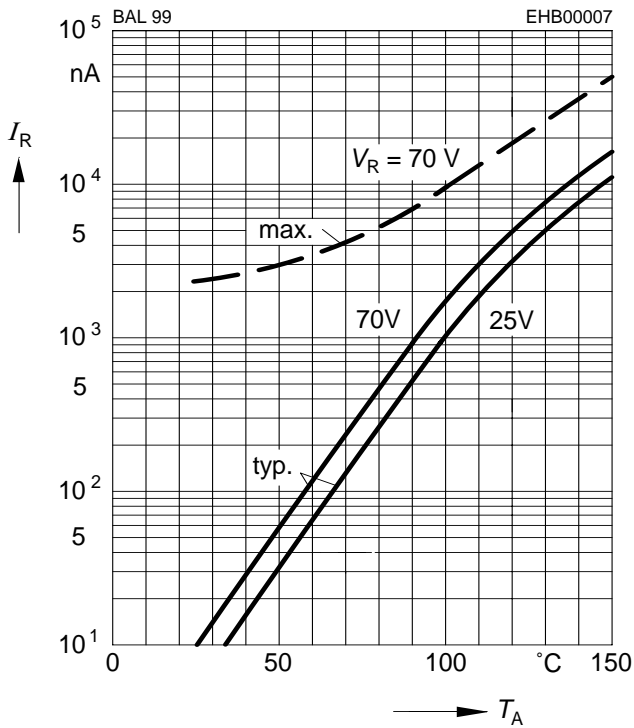
**Test circuit for reverse recovery time**


Puls generator:  $t_p = 100\text{ns}$ ,  $D = 0.05$ ,  
 $t_r = 0.6\text{ns}$ ,  $R_i = 50\Omega$

Oscilloscope:  $R = 50$ ,  $t_r = 0.35\text{ns}$   
 $C \leq 1\text{pf}$

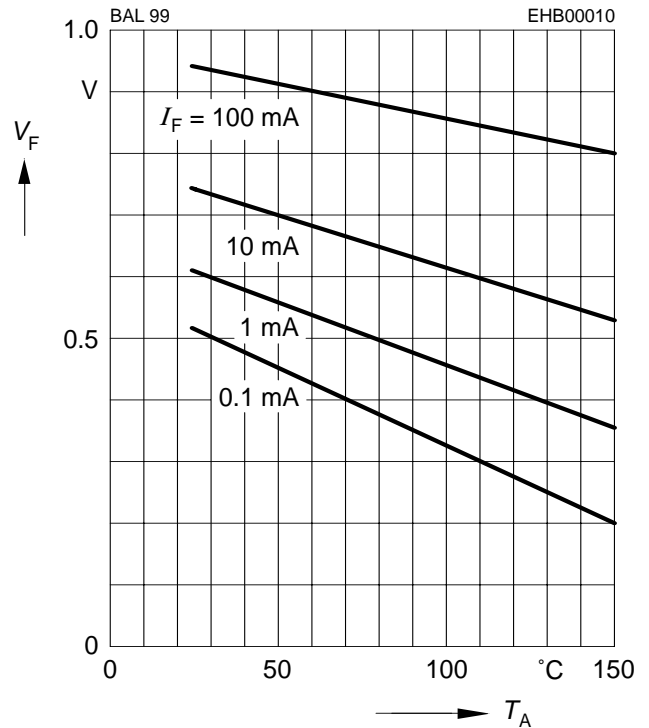
**Reverse current  $I_R = f(T_A)$**

$V_R = \text{Parameter}$

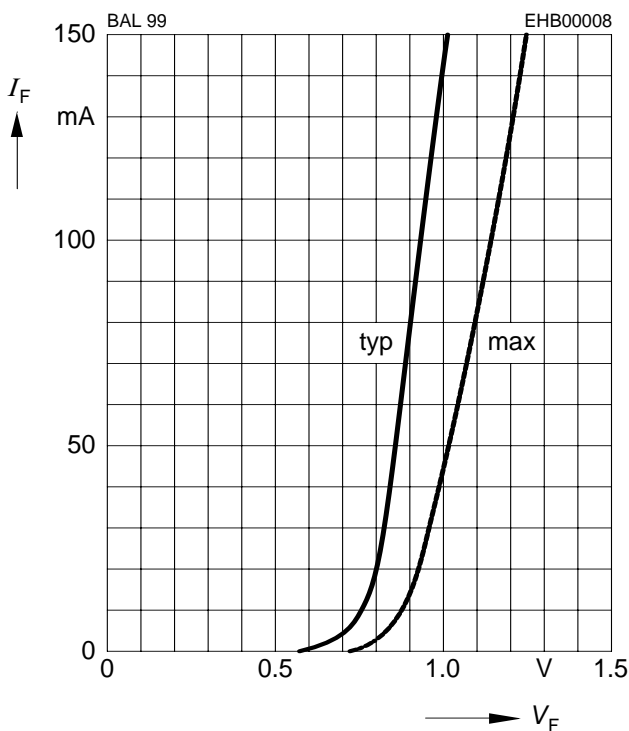


**Forward Voltage  $V_F = f(T_A)$**

$I_F = \text{Parameter}$

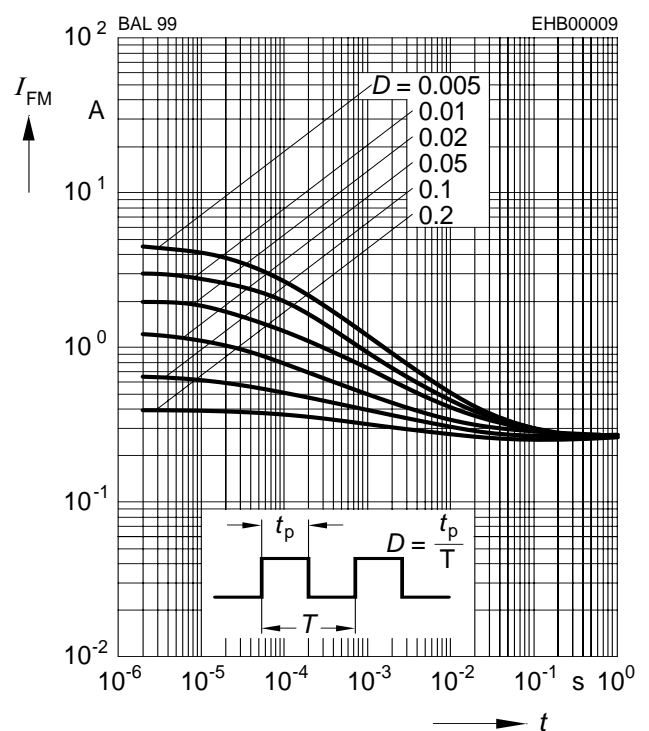


**Forward current  $I_F = f(V_F)$**

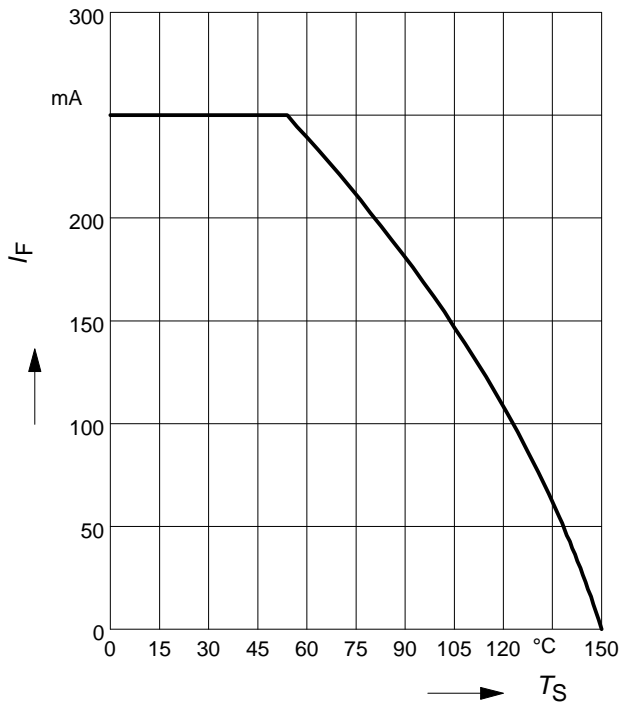


**Peak forward current  $I_{FM} = f(t_p)$**

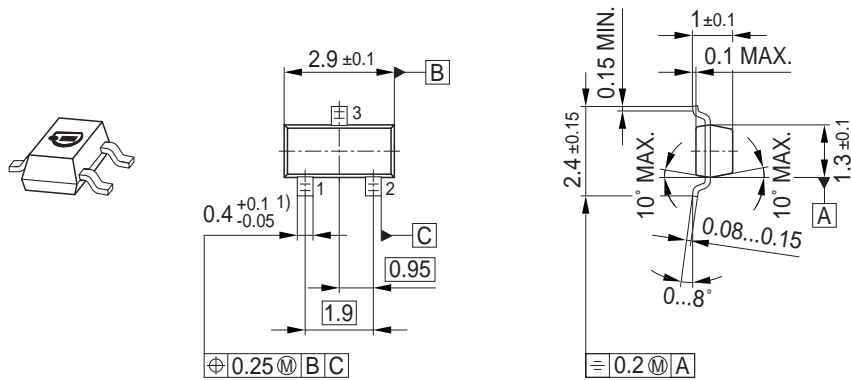
$T_A = 25^\circ\text{C}$



Forward current  $I_F = f(T_S)$

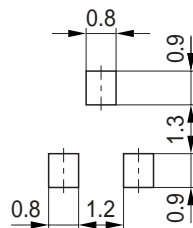


Package Outline

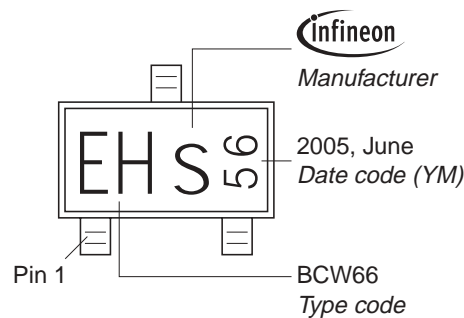


1) Lead width can be 0.6 max. in dambar area

Foot Print

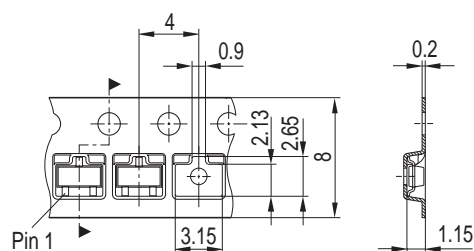


Marking Layout (Example)



Standard Packing

Reel  $\varnothing$ 180 mm = 3.000 Pieces/Reel  
 Reel  $\varnothing$ 330 mm = 10.000 Pieces/Reel



Edition 2006-02-01  
Published by  
Infineon Technologies AG  
81726 München, Germany  
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